MA1U152WA

Silicon epitaxial planer type

For switching circuits

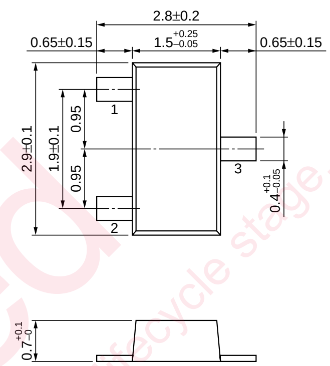
■ Features

- Package thickness as small as 0.7mm, most favorite for thinning of equipment
- Flat lead type, with improved mounting efficiency and solderability in the high-speed mounting machine
- Anode common connection type

■ Absolute Maximum Ratings (Ta= 25˚C)

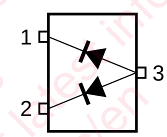
Parameter		Symbol	Rating	Unit
Reverse voltage (DC)		V_R	80	V
Peak reverse voltage		V_{RM}	80	V
Forward current (DC)	Single	I_F	100	mA
	Double		150	
Peak forward current	Single	I_{FM}	225	mA
	Double		340	
Non-repetitive peak forward surge current	Single	I_{FSM} *	500	mA
	Double		750	
Junction temperature		T_j	150	˚C
Storage temperature		T_{stg}	– 55 to +150	˚C

* t=1s



Marking Symbol : MO

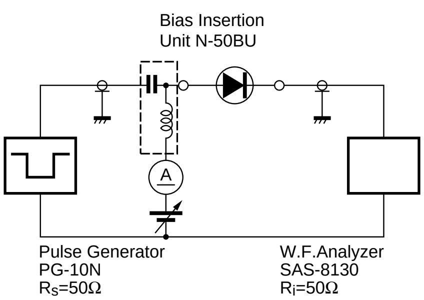
■ Internal Connection

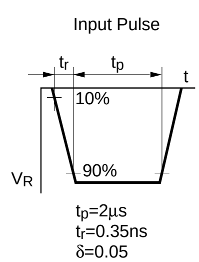


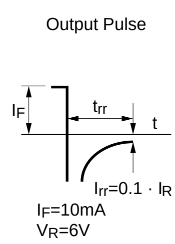
■ Electrical Characteristics (Ta= 25˚C)

Parameter	Symbol	Condition	min	typ	max	Unit
Reverse current (DC)	I_R	V_R= 75V			0.1	µA
Forward voltage (DC)	V_F	I_F=100mA			1.2	V
Reverse voltage (DC)	V_R	I_R=100µA	80			V
Terminal capacitance	C_t	V_R= 0V, f=1MHz			15	pF
Reverse recovery time	t_{rr}*	I_F=10mA, V_R= 6V I_{rr}= 0.1 · I_R, R_L=100Ω			10	ns

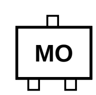
Note 1 : Rated input/output frequency : 100MHz
2 : * t_{rr} measuring circuit



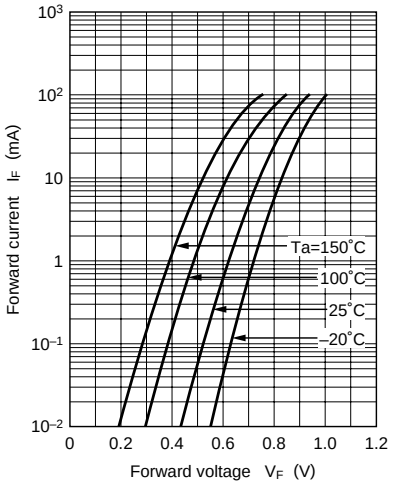




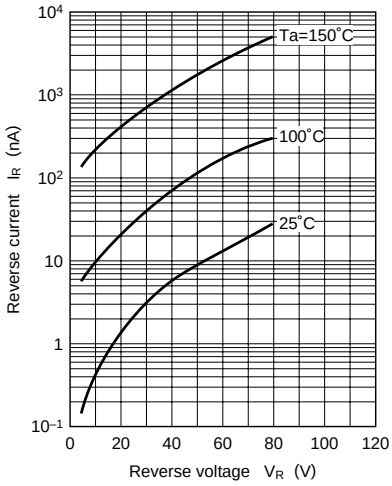
■ Marking



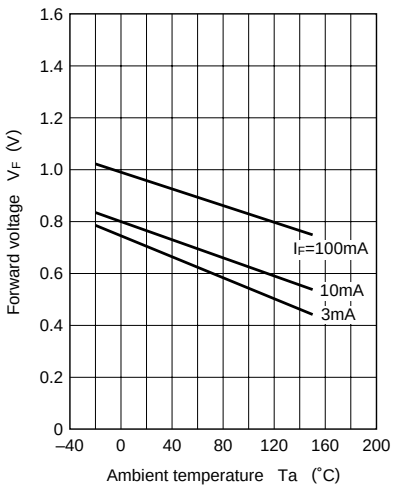
$I_F - V_F$



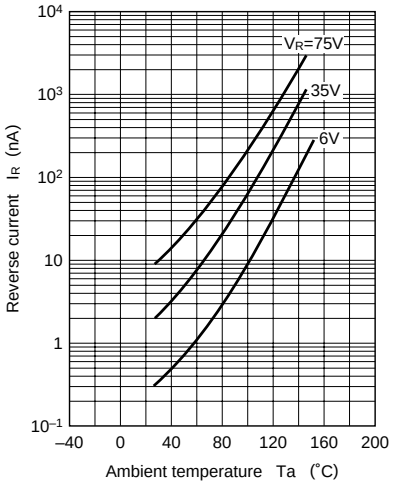
$I_R - V_R$



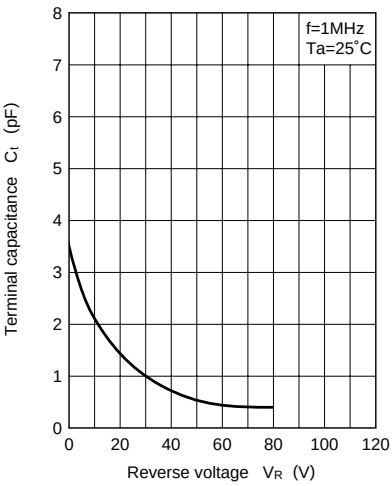
$V_F - Ta$



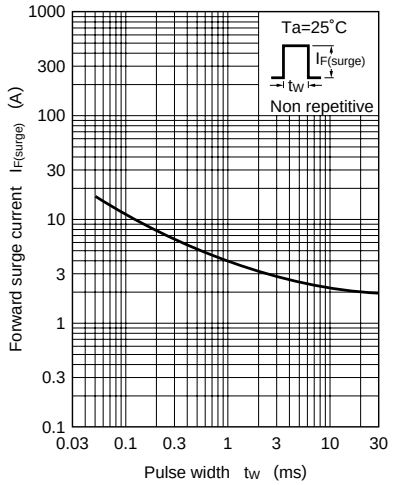
$I_R - Ta$



$C_t - V_R$



$I_{F\,(surge)} - t_W$



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